



# Raven-Strike® II

## Enterprise Server-Class Mission Computer



Lifecycle Stage: Active | Pre-Qualified Production

[systelusa.com/raven-strike-ii](http://systelusa.com/raven-strike-ii)

### Product Brief

Raven-Strike II is a MIL-SPEC rugged server-class compute solution, purpose-built for highly intensive workloads in austere environments.

Configured with the latest gen Intel Xeon SP CPU and NVIDIA GPU, Raven-Strike II features server-class processing capability to power mission-critical applications. Raven-Strike II is highly configurable with robust IO capabilities, including high-bandwidth networking. Raven-Strike II also offers up to (4) high-capacity, high-speed removable SSDs to securely store mission data.

Raven-Strike II is engineered to withstand the harshest environments on the planet, bringing data center compute to the tactical edge.



### Key Features

- Size: 11.7"W x 18.2"D x 7.9"H
- Weight: ~37bs (configuration dependent)
- Processing: 3rd gen Intel Xeon SP CPU (up to 205W) and NVIDIA Ampere GPU (up to 230W)
- Power: integrated DC/DC power supply, 28VDC nominal
- Immense IO and configurability options including multiple USB 3.0, 10GbE, DP++; system expansion options include up to 100GbE fiber, video capture and encode, GbE switch, GPS
- Up to (4) removable high-capacity SSDs
- MIL-SPEC rugged and fully sealed
- Operating temperature up to -40C to +55C (active cooled with heaters)
- Engineered with a standards-based approach utilizing open architectures and COTS technologies
- Designed using a Modular Open Systems Approach (MOSA)

# Raven-Strike II Specifications

Model Number: EC7410

Systel 3-Year Product Warranty  
EOL and Configuration Management Included



## System Specs

### Chassis

- Material: machined aluminum
- Finish: black anodized exterior, clear alodine interior
- Mounting: base mounting

### SWAP (base model)

- Chassis Dimensions: 11.71"W (13.42" with mounting) x 18.17"D (19.819" with connectors) x 7.905"H
- Weight: ~37lbs (config dependent)
- Power: 28VDC, standard config max power ~500W, max system power 820W (galvanically isolated power supply)

### Processing

- microATX motherboard
- (1) 3rd gen Intel Xeon scalable processor up to 205W TDP
- (1) NVIDIA Ampere GPU up to 230W TDP
- Up to 1TB ECC RDIMM DDR4-3200 memory
- (1) Server Trusted Platform Module (TPM) 2.0

### OS

- Supports Windows and Linux 64-bit (please consult with a Systel sales representative for specific OS requirements)

### Base System IO

- USB: (2) USB 3.0, (4) USB 2.0
- Ethernet: (2) 10GbE, (4) GbE, (1) IPMI GbE
- Serial: (1) RS232
- Video Output: (4) Display Port (from GPU), (1) VGA (onboard)

### Connectors

MIL-DTL-38999 for IO and power (power located on rear side of system); rugged circular field for USB 3.0 and 10GbE; rugged RF connector options available

### System Expansion

Numerous options including up to 100GbE fiber, video capture and encode, GbE switch, GPS

- (2) PCIe 4.0 x16
- (1) m.2 x4 m-key 2242/2280
- Other interfaces available (ex: USB)

### Storage

- Up to (4) removable 2.5" SSDs (2 drive bays), SATA III up to 4TB each, FIPS 140-2 options
- Internal (non-removable) 1TB m.2 NVME option

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## Environmental Specs

|                            |  |
|----------------------------|--|
| <b>Operating Temp</b>      | Tested to -40C to +55C (forced air convection cooled with internal heaters and stir fans) MIL-STD-810H, Method 501.7, Proc. II; Method 502.7, Proc. II |
| <b>Non-Operating Temp</b>  | -55C to +85C<br>MIL-STD-810H, Method 501.7, Proc. I; Method 502.7, Proc. II  |
| <b>Vibration</b>           | Tested to MIL-STD-810H, Method 514.8, Proc. I, Cat. 4, C-II, Common Carrier (US highway truck vibration)   |
| <b>Shock, Functional</b>   | MIL-STD-810H, Method 516.8, Proc. I, 40g at 11ms, Ground   |
| <b>Shock, Crash Hazard</b> | MIL-STD-810H, Method 516.8, Proc. V 75g at 6ms, Ground   |
| <b>Altitude</b>            | MIL-STD-810H, Method 500.6, Proc. II, 50k feet*, Operating;<br><i>*thermal derating may occur</i>  |
| <b>Humidity</b>            | MIL-STD-810H, Method 507.6-7, Proc. II, RH 95%, 60C, Aggravated  |
| <b>Sand and Dust</b>       | MIL-STD-810H, Method 510.7, Proc. I and II; IP6X: IEC60529:2013 Section 4.2.7  |
| <b>Fluid Ingress</b>       | MIL-STD-810H, Method 506.6, Proc. II; IPx7: IEC60529:2013 Section 4.2.7  |
| <b>EMI/EMC</b>             | MIL-STD-461G, CE101, CE102, CS101, CS114, CS115, CS116, RE101, RE102, RS101, RS103   |
| <b>Power</b>               | MIL-STD-1275E;<br>MIL-HDBK-704-8 <i>*no power hold-up</i>  |

Unless otherwise noted, all environmental specifications are designed to meet with testing pending. "Qualified to" indicates that certified 3rd party testing has been successfully completed. "Tested to" indicates that Systel internal testing has been successfully completed. All testing completed on base model unit(s).



# SYSTEL

Any **Mission.** Anywhere.

All specifications are configuration-dependent and subject to change. Please contact a Systel sales representative to discuss your configuration.

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